



COMe-8X92 COM Express Module and COMEDB2 Carrier Board Reference

Quick Guide

Key Features:

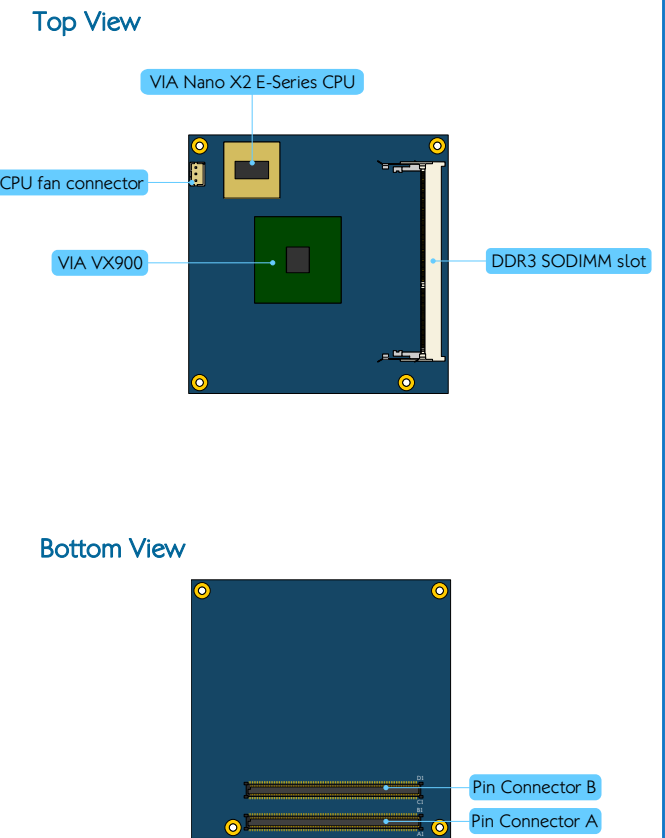
- 1.2GHz VIA Nano® X2 E-Series processor
- Supports up to 4GB 1066 DDR3 SDRAM
- DX9 3D/2D graphics with MPEG-2, WMV9, VC1 and H.264 decoding acceleration
- Display interface for VGA, 18/24-bit single-channel LVDS panel, one DisplayPort and one HDMI® port
- Supports four USB 3.0 and four USB 2.0 ports

COMe-8X92 Module Specifications

Core	
Processor	<ul style="list-style-type: none"> ▪ 1.2GHz VIA Nano® X2 E-Series ▪ 1.0GHz VIA QuadCore E-Series (manufacturing option)
Chipset	▪ VIA VX900 all-in one system processor
System Memory	<ul style="list-style-type: none"> ▪ 1 x DDR3 1066 SODIMM slot ▪ Supports up to 4GB memory size
BIOS	<ul style="list-style-type: none"> ▪ AMI BIOS ▪ 4/8Mbit SPI flash memory
Operating System	<ul style="list-style-type: none"> ▪ Windows 7 ▪ Windows Embedded System 7 ▪ Windows CE 6.0 ▪ Linux ▪ QNX Neutrino ▪ VXWorks 6.9
Hardware Monitoring	<ul style="list-style-type: none"> ▪ CPU temperature reading ▪ CPU fan speed reading ▪ System voltage monitoring
Watchdog Timer	▪ Software Programmable
Expansion Bus	<ul style="list-style-type: none"> ▪ 1 x PCIe Gen2 x4 ▪ 1 x PCIe Gen2 x1
Video	
VGA	▪ Integrated VIA C-9 HD DX9 3D/2D graphics processor and unified video decoding accelerator
CRT Interface	▪ 1 x VGA port supports up to 2560x1600 resolution
LVDS Interface	▪ 1 x LVDS channel supports single-channel 8-bit or 24-bit LVDS panel
HDMI® Interface	▪ 1 x HDMI® port
DisplayPort Interface	▪ 1 x DisplayPort
Expansion Bus	▪ 1 x Digital Video Output port for external HDMI®/LVDS/DVI transmitter or TV encoder

Ethernet	
Chipset	▪ VIA VT6130 Gigabit Ethernet controller
Input/Output	
Audio	▪ 1 x HD audio digital interface
LAN	▪ 1 x Gigabit Ethernet port
USB	<ul style="list-style-type: none"> ▪ 4 x USB 3.0 ports by (VLI VL800 controller) ▪ 4 x USB 2.0 ports
SATA	▪ 2 x SATA 3.0 Gbps connectors
Serial	▪ 2 x Serial ports with TX and RX signals
Expansion Buses	<ul style="list-style-type: none"> ▪ 1 x SMBus interface ▪ 1 x I²C bus ▪ 1 x SDIO interface (default) ▪ 1 x GPIO interface with 4 IN's and 4 OUT's, shared with SDIO (by request) ▪ 1 x LPC bus interface ▪ 1 x SPI ▪ Support ExpressCard, speaker out, reset function, thermal protection, suspend/wake signals, power button, power good and fan control signals
Mechanical and Environment	
COM Express Compliance	▪ COM Express™ Type 6, Basic Module
Dimension	▪ 95mm x 95mm (3.73" x 3.73")
Operating Temperature	▪ 0°C ~ 50°C
Storage Temperature	▪ -40°C ~ 70°C
Operating Humidity	▪ 0% ~ 95% (relative humidity; non-condensing)

COMe-8X90 Module Layout Diagram



COMEDB2 Carrier Board Specifications

COM Express Module Type	
	▪ Support COM Express™ Type 6
Audio	
	▪ VIA VT1828S High Definition Audio Codec
Super I/O	
	▪ VIA VT1211 LPC Super IO
BIOS	
	<ul style="list-style-type: none"> ▪ AMI BIOS ▪ 4/8Mbit LPC Flash BIOS, PLCC 32 pin or SPI BIOS
Front Panel I/O	
	▪ 1 x SD card slot (SDIO), shared with DIO1 pin header
Rear Panel I/O	
	<ul style="list-style-type: none"> ▪ 1 x VGA port ▪ 1 x COM port ▪ 1 x DisplayPort ▪ 1 x HDMI® port ▪ 4 x USB 3.0 ports ▪ 1 x Gigabit Ethernet port ▪ 6 x Audio jacks (supports multi-channel audio outputs)
Onboard Slots, Buttons and Power Connectors	
	<ul style="list-style-type: none"> ▪ 1 x ATX power connector ▪ 1 x AUX power connector ▪ 1 x miniPCIe slot ▪ 1 x Power button ▪ 1 x Reset button ▪ 2 x SATA connectors ▪ 1 x Reserved PCIe x4 slot for DVP ▪ 1 x Reserved PCIe x4 slot for VCP ▪ 2 x PCIe x1 slots ▪ 1 x PCIe x16 (supports 4-Lane) slot for PEG

Onboard Pin Headers and Connectors

- 1 x COM2 pin header, add +5V/+12V power select option on RI pin
- 1 x LPT pin header
- 1 x SPI pin header
- 1 x LPC pin header
- 1 x DIO1 pin header, shared with SDIO port
- 1 x DIO2 pin header (from VIA VT1211)
- 1 x SMBus pin header
- 1 x I²C pin header
- 2 x USB 2.0 pin headers for USB 2.0 port 0~3
- 1 x Front LAN LED pin header
- 1 x Front Audio pin header
- 1 x Front Panel pin header (for HDD LED, Power LED, Switch and Speaker)
- 1 x CD-In connector
- 1 x System sensor pin header
- 1 x CPU fan connector
- 1 x System fan connector
- 1 x Serial Port pin header
- 1 x Inverter connector
- 1 x LVDS panel connector
- 1 x S/PDIF connector

Onboard Jumpers

- 1 x Clear CMOS jumper
- 1 x Inverter power select jumper
- 1 x LCD panel power select jumper
- 2 x BIOS type select jumpers (for select LPC/SPI BIOS)
- 2 x BIOS select jumpers (for select module/carrier board BIOS)
- 2 x COM voltage select jumpers
- 1 x TV/DVP select jumper
- 2 x USB 2.0 port select jumpers
- 1 x USB 2.0 to miniPCIe slot select jumper

Form Factor and Dimension

- Micro-ATX
- 10" x 9.6"

Operating Temperature

- 0°C ~ 60°C

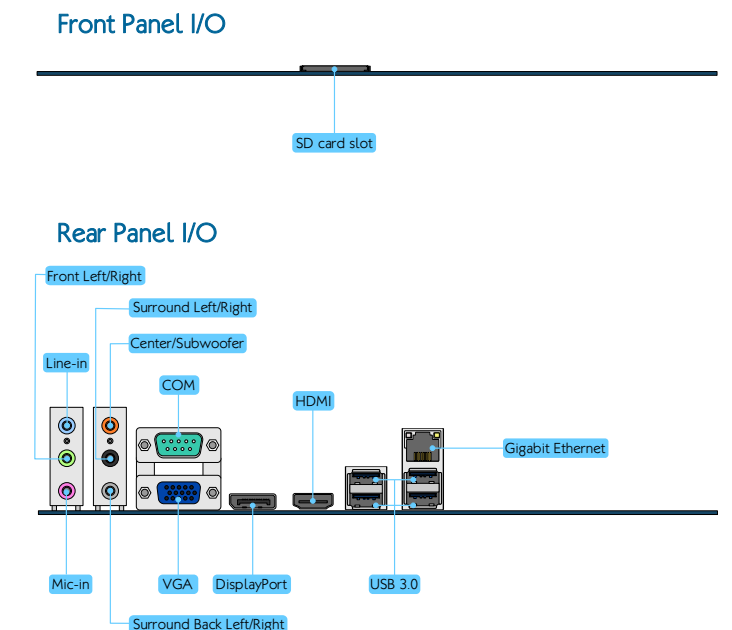
Storage Temperature

- -40°C ~ 70°C

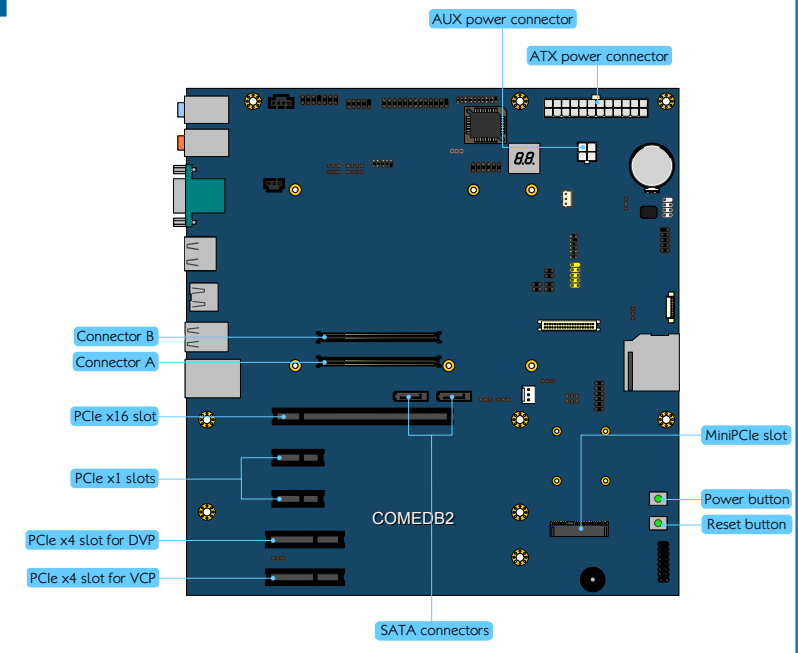
Operating Humidity

- 0% ~ 95% relative humidity

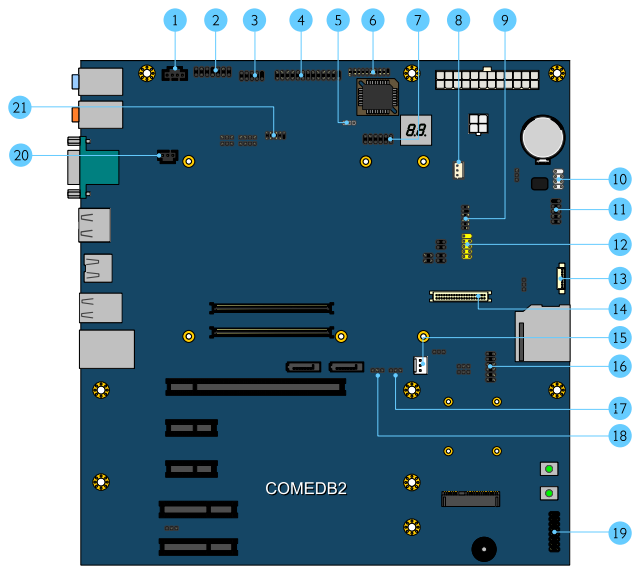
COMEDB2 Carrier Board Layout Diagram



Onboard Slots, Buttons and Power Connectors



Onboard Pin headers and Connectors



6 LPC

LPC_AD1	1	LPC_33M_CLK	2
-LPC_RESET	3	GND	4
LPC_AD0	5	NC	6
LPC_AD2	7	-LPC_FRAME	8
LPC_SERIRQ	9	LPC_AD3	10
-LPC_DRQ1	11	NC	12
+5V	13	+3.3V	14
+5V	15	+3.3V	16
GND	17	GND	18
GND	19	KEY	20

7 DIO2

5V_DIO2	1	12V_DIO2	2
SIO_GPO30	3	SIO_GPI34	4
SIO_GPO31	5	SIO_GPI35	6
SIO_GPO32	7	SIO_GPI36	8
SIO_GPO33	9	SIO_GPI37	10
GND	11	GND	12

8 CPUFAN

1	FANIO
2	FANPWM
3	GND

9 USB2_0/1

VUSB	1	VUSB	2
USBD_T4-	3	USBD_T5-	4
USBD_T4+	5	USBD_T5+	6
GND	7	GND	8
KEY	9	W_LESS_LED	10
GND	11	-RF_ON	12

10 SPI

SPI_VCC	1	GND	2
-SPI_SS0	3	SPI_CLK	4
SPI_DI	5	SPI_DO	6
KEY	7	RESET	8

11 SER_PORT

SER0_TX_CON	1	SER0_RX_CON	2
NC	3	NC	4
GND	5	NC	6
SER1_TX_CON	7	SER1_RX_CON	8
NC	9	KEY	10

12 USB2_2/3

VUSB	1	VUSB	2
USBD_T6-	3	USBD_T7-	4
USBD_T6+	5	USBD_T7+	6
GND	7	GND	8
KEY	9	GND	10

13 Inverter

1	IVDD_IN
2	IVDD_IN
3	BAKLITE_EN
4	BLT_CK
5	BAKLITE_EN
6	BLT_CTRL
7	GND
8	GND

14 LVDS

NC-	1	PVDD	2
NC	3	PVDD	4
GND	5	GND	6
NC	7	GND	8
NC	9	-A0_L	10
GND	11	A0_L	12
NCL	13	GND	14
NC	15	-A1_L	16
GND	17	A1_L	18
NC	19	GND	20
NC	21	-A2_L	22
GND	23	A2_L	24
NC	25	GND	26
NC	27	-CLK1_L	28
NC	29	CLK1_L	30
NC	31	GND	32
NC	33	-A3_L	34
NC	35	A3_L	36
NC	37	SPCLK	38
NC	39	SPD	40

15 SYSFAN

1	FANIO
2	FANPWM
3	GND

16 DIO1

5V_DIO1	1	12V_DIO1	2
COM_GPO0	3	COM_GPI0	4
COM_GPO1	5	COM_GPI1	6
COM_GPO2	7	COM_GPI2	8
COM_GPO3	9	COM_GPI3	10
GND	11	GND	12

17 I2C_BUS

1	I2C_CLK
2	I2C_DATA
3	GND

18 SMBUS

1	SMB_CLK
2	SMB_DATA
3	GND

19 F_PANEL

FP_5V	1	FP_3V	2
FP_5V	3	-SATA_LED	4
-PLED	5	-PW_BTN	6
FP_5V	7	GND	8
NC	9	RST_SW	10
NC	11	GND	12
SPEAK	13	FP_5V	14
KEY	15	NC	16

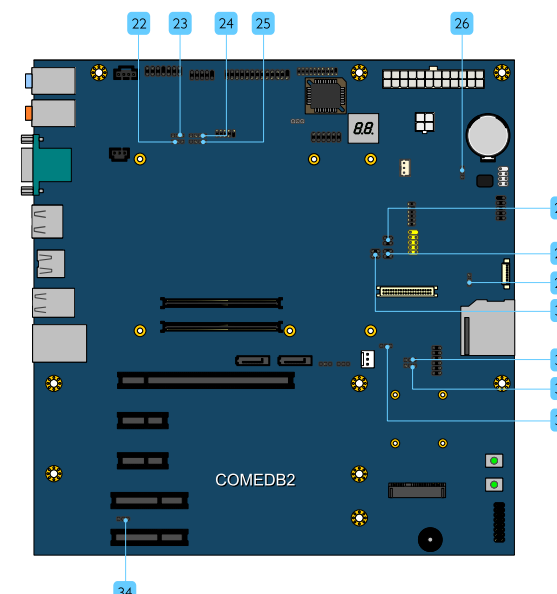
20 SPDIF

1	+5V
2	SPDIFO
3	GND

21 FLAN_LED

3VSUS	1	-LAN_ACT	2
3VSUS	3	NC	4
GND	5	W_LAN_LED	6
3VSUS	7	GND	8
KEY	9	GND	10

Onboard Jumpers



22 BIOS_SELO

Pins	Description
1-2	2-3 Select SPI BIOS (default)
2-3	1-2 Select LPC BIOS

24 JP_COM2_VSEL

Pins	Description
1-2	Enabled COM2 pin header to support +5V
2-3	Normal (default)
3-4	Enabled COM2 pin header to support +12V

25 JP_COM1_VSEL

Pins	Description
1-2	Enabled COM1 connector to support +5V
2-3	Normal (default)
3-4	Enabled COM1 connector to support +12V

23 BIOS_SEL1

26 CLEAR_CMOS

Pins	Description
1-2	Keep CMOS settings (default)
2-3	Clear CMOS settings

27 JP_USB3_SEL

Pins	Description
1-2	Enabled USB 2.0 Port 3 (USB2_3). (default)
3-4	Enabled USB 2.0 Port 3 (USB2_3). (default)

28 JP_USB2_SEL

Pins	Description
1-2	Enabled USB 2.0 Port 2 (USB2_2). (default)
3-4	Enabled USB 2.0 Port 2 (USB2_2). (default)

Note: For [28] JP_USB2_SEL to be activated, the [30] JP_USBME_SEL function has to be disabled.

29 IVDD

Pins	Description
1-2	Use +5V for the Inverter power
2-3	Use +12V for the Inverter power (default)

30 JP_USBME_SEL

Pins	Description
1-2	Enabled USB 2.0 Port 2 to miniPCle slot.
3-4	Enabled USB 2.0 Port 2 to miniPCle slot.

Note: For [30] JP_USBME_SEL to be activated, the [28] JP_USB2_SEL function has to be disabled.

31 BIOS_DIS1

Pins	Description
1-2	1-2 Select module SPI BIOS (default)
1-2	2-3 Select carrier board LPC BIOS
2-3	1-2 Select module LPC BIOS
2-3	2-3 Select carrier board SPI BIOS

32 BIOS_DIS0

33 PVDD

Pins	Description
1-2	Use +5V for the LCD panel power.
2-3	Use +3.3V for the LCD panel power (default)

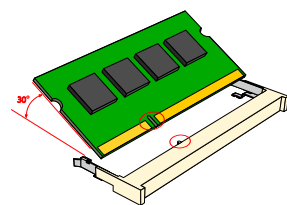
34 TV_DVP_SEL

Pins	Description
1-2	Enabled TTL/TV support from DVP slot
2-3	Plug detect from DVP slot (default)

1 Installing SODIMM memory on COMe-8X92 module

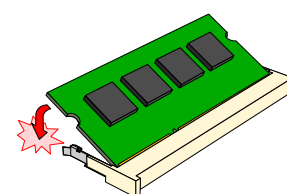
Step 1

Align the notch on the memory module with the protruding wedge on the SODIMM slot. Insert the memory module into the socket at 30 degrees angle.



Step 2

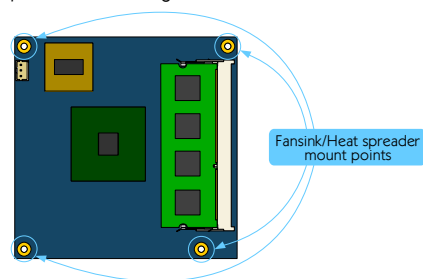
Push down until the memory module snaps into place. The memory slot has two locking mechanisms that will click once the memory module has been fully inserted.



2 Installing COMe-8X92 module to COMEDB2 carrier board

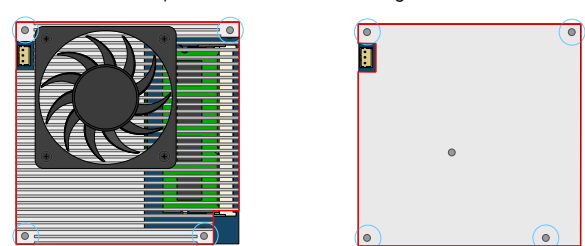
Step 1

Locate the fansink/heat spreader mounting holes on the COMe-8X92 module.



Step 2

Align the fansink/heat spreader over the mounting holes.



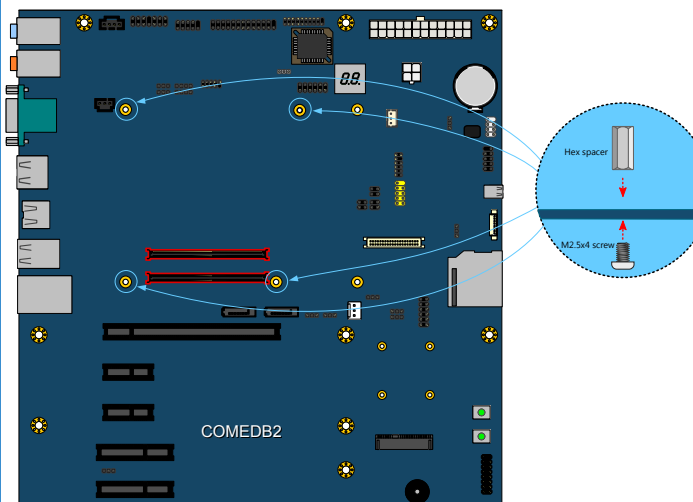
Note: Make sure the thermal pad or thermal paste has been applied on top of the processor and chipset before installing the fansink/heat spreader.

Step 3

Locate the carrier board mounting points (x4) and the connectors (x2).

Step 4

Install the hex spacer onto the carrier board. The hex spacer must be placed on top of the board. From the bottom of the board, tighten the hex spacers by using the M2.5x4 screws (x4).

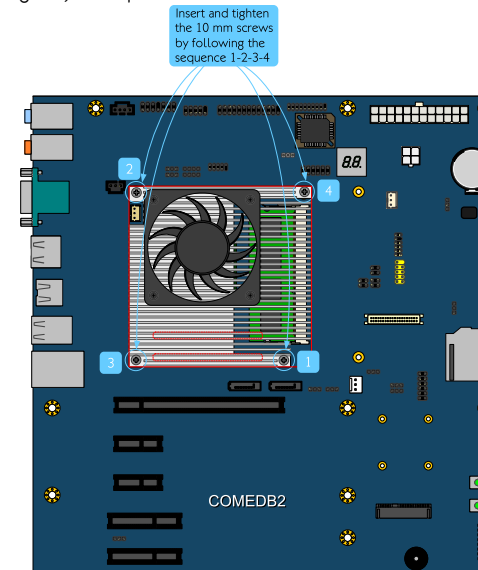


Step 5

Align the pin connectors and mounting points of the COMe-8X92 into the connectors and hex spacers on the carrier board respectively.

Step 6

Press down the COMe-8X92 module until the pin connectors have been fully inserted into the connectors. Secure the COMe-8X92 module with the fansink/heat spreader by screwing and tightening four screws 10mm screws (torque: 3kgfcm) in sequence.



VIA Technologies, Inc.
1F, 531, Zhong-zheng Road, Xindian District,
New Taipei City 231, Taiwan
Tel: 886-2-2218-5452
Fax: 886-2-2218-5453
Web: www.viatech.com

For more information on this and other VIA products, please visit www.viatech.com